

AMENDMENTS TO THE CLAIMS

Claims 1-8 (Cancelled).

9. (Currently Amended) An interconnecting structure comprising:
first wirings supported by a substrate;
a low-k dielectric film on the first wirings, the low-k dielectric film having a dielectric constant not exceeding 3;
a cap film on the low-dielectric film;
vias in the low-k dielectric film ~~and in the cap film~~, the vias being ~~connected~~ to contacting the first wiring;
~~second wirings on the vias~~ partially within the low-k dielectric film and connected to the vias, the second wiring being partially within the cap film and having a surface_coplanar with a surface of the cap film; and
dummy vias on the periphery of an isolated via of the vias.

10. (Previously Presented) The interconnecting structure according to claim 9, wherein all of the first wirings, the vias, the second wirings, and the dummy vias have a damascene structure.

Claims 11-12 (Cancelled).

This listing of claims replaces all prior versions, and listings, of claims in the application.